

# 1.5V Drive Pch MOSFET

## RQ1A070ZP

### ●Structure

Silicon P-channel MOSFET

### ●Features

- 1) Low On-resistance.
- 2) Low voltage drive. (1.5 V)
- 3) High power package.

### ●Applications

Switching

### ●Packaging specifications

Type	Package	Taping
		Code
	Basic ordering unit (pieces)	3000
RQ1A070ZP		○

### ●Absolute maximum ratings (Ta=25°C)

<It is the same ratings for Tr1 and Tr2.>

Parameter	Symbol	Limits	Unit	
Drain-source voltage	$V_{DSS}$	-12	V	
Gate-source voltage	$V_{GSS}$	±10	V	
Drain current	Continuous	$I_D$	±7	A
	Pulsed	$I_{DP}$ *1	±28	A
Source current (Body diode)	Continuous	$I_S$	-1	A
	Pulsed	$I_{SP}$ *1	-28	A
Total power dissipation	$P_D$ *2	1.5	W	
Channel temperature	$T_{ch}$	150	°C	
Range of Storage temperature	$T_{stg}$	-55 to +150	°C	

\*1  $P_{ws} \leq 10 \mu s$ , Duty cycles  $\leq 1\%$

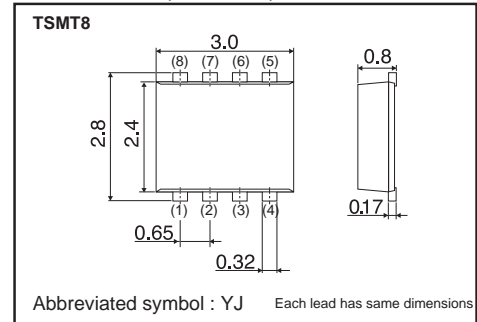
\*2 When mounted on a ceramic board

### ●Thermal resistance

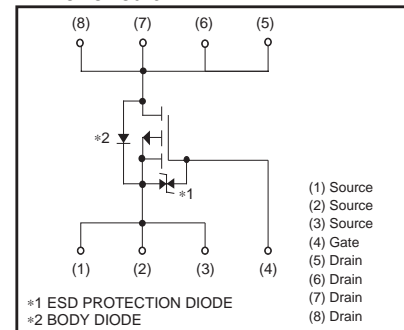
Parameter	Symbol	Limits	Unit
Channel to ambient	$R_{th(ch-a)}$ *	83.3	°C/W

\* Mounted on a ceramic board.

### ●Dimensions (Unit : mm)



### ●Inner circuit



## ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	-	-	±10	μA	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	-12	-	-	V	I <sub>D</sub> =-1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	-1	μA	V <sub>DS</sub> =-12V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	-0.3	-	-1.0	V	V <sub>DS</sub> =-6V, I <sub>D</sub> =-1mA
Static drain-source on-state resistance	R <sub>DS(on)</sub> *	-	8	12	mΩ	I <sub>D</sub> =-7A, V <sub>GS</sub> =-4.5V
		-	11	16	mΩ	I <sub>D</sub> =-3.5A, V <sub>GS</sub> =-2.5V
		-	15	23	mΩ	I <sub>D</sub> =-3.5A, V <sub>GS</sub> =-1.8V
		-	19	38	mΩ	I <sub>D</sub> =-1.4A, V <sub>GS</sub> =-1.5V
Forward transfer admittance	Y <sub>fs</sub>   *	12	-	-	S	V <sub>DS</sub> =-6V, I <sub>D</sub> =-7A
Input capacitance	C <sub>iss</sub>	-	7400	-	pF	V <sub>DS</sub> =-6V
Output capacitance	C <sub>oss</sub>	-	800	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>riss</sub>	-	750	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	-	35	-	ns	V <sub>DD</sub> ≐-6V
Rise time	t <sub>r</sub> *	-	95	-	ns	I <sub>D</sub> =-3.5A
Turn-off delay time	t <sub>d(off)</sub> *	-	310	-	ns	V <sub>GS</sub> =-4.5V
Fall time	t <sub>f</sub> *	-	190	-	ns	R <sub>L</sub> ≐1.7Ω
Total gate charge	Q <sub>g</sub> *	-	58	-	nC	V <sub>DD</sub> ≐-6V
Gate-source charge	Q <sub>gs</sub> *	-	11	-	nC	I <sub>D</sub> =-7A
Gate-drain charge	Q <sub>gd</sub> *	-	10	-	nC	V <sub>GS</sub> =-4.5V
						R <sub>L</sub> ≐0.86Ω / R <sub>G</sub> =10Ω

\* Pulsed

## ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	-	-	-1.2	V	I <sub>S</sub> =-7A, V <sub>GS</sub> =0V

\* Pulsed

●Electrical characteristics curves

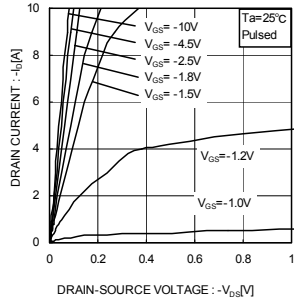


Fig.1 Typical output characteristics ( I )

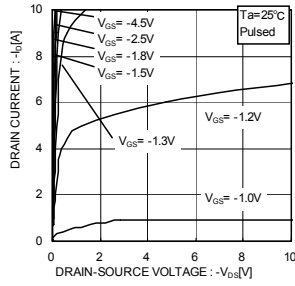


Fig.2 Typical output characteristics ( II )

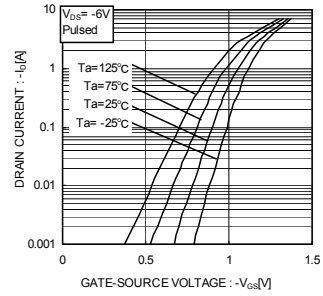


Fig.3 Typical Transfer Characteristics

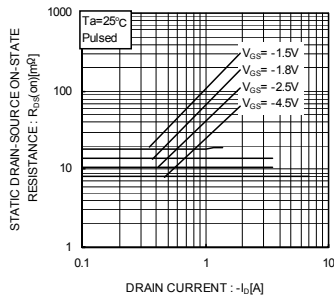


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

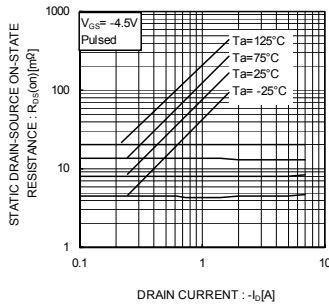


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

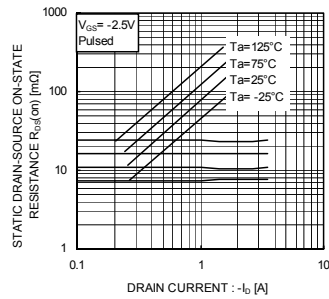


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III )

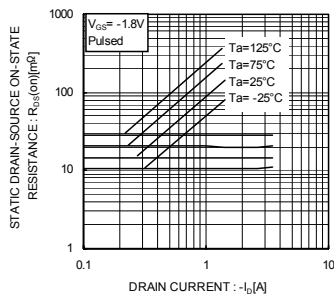


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current( IV )

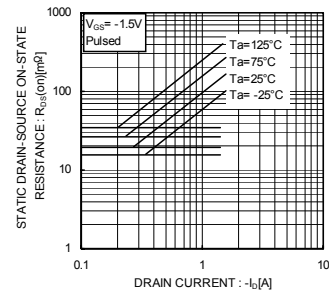


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current( V )

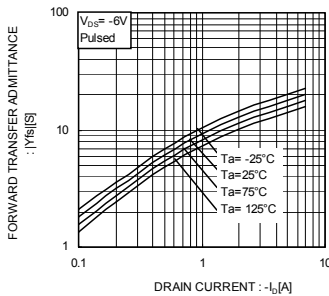


Fig.9 Forward Transfer Admittance vs. Drain Current

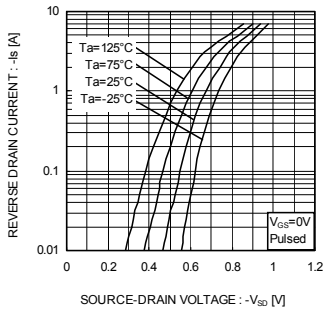


Fig.10 Reverse Drain Current vs. Source-Drain Voltage

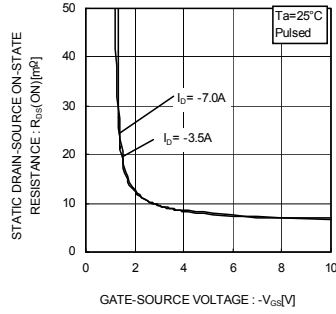


Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

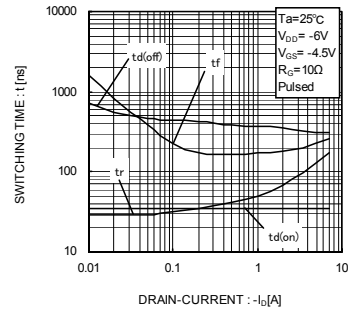


Fig.12 Switching Characteristics

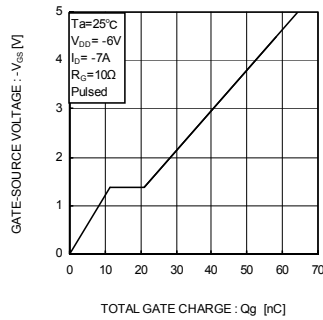


Fig.13 Dynamic Input Characteristics

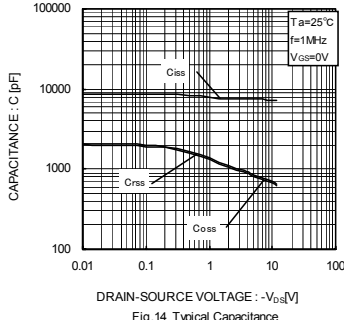


Fig.14 Typical Capacitance vs. Drain-Source Voltage

●Measurement circuits

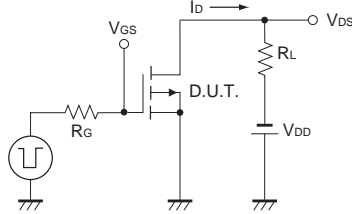


Fig.1-1 Switching Time Measurement Circuit

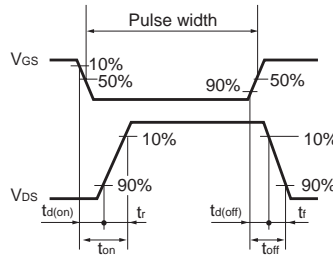


Fig.1-2 Switching Waveforms

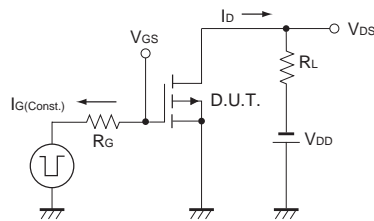


Fig.2-1 Gate Charge Measurement Circuit

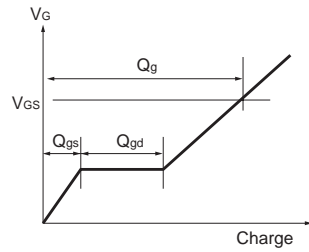


Fig.2-2 Gate Charge Waveform

●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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